

'HOME' ENTERED AT 11:34:49 ON 10 MAR 1999)

FILE 'INSPEC' ENTERED AT 11:35:01 ON 10 MAR 1999  
L1 45733 IMPLANT?  
L2 8743 CADMIUMTELLURIDE OR CDTE  
L3 13953 (AR OR ARGON) (4A) (ION# OR ATOM#)  
L4 1600 CADMIUM TELLURIDE  
L5 9195 L2 OR L4  
L6 138697 OBLIQUE OR ANGLE  
L7 1321 L1(P)L3  
L8 58 L7(P)L6  
L9 0 L5 AND L8  
L10 58 L7 AND L6  
L11 0 L5 AND L10  
L12 117588 45 OR 90  
L13 8 L10(P)L12  
L14 0 FILW WPIDS

FILE 'WPIDS' ENTERED AT 11:41:58 ON 10 MAR 1999  
L15 5 L10

FILE 'CA' ENTERED AT 11:43:51 ON 10 MAR 1999  
L16 80 L10  
L17 0 L16 AND L5  
L18 5413 COMPOUND SEMICONDUCTOR#  
L19 0 L17 AND L18  
L20 649821 SEMICONDUCTOR# OR SILICON  
L21 5413 L18 AND L20  
L22 0 L16 AND L21  
L23 31 L16 AND L20

=> d 123 5, 11, 14, 22 all

L23 ANSWER 5 OF 31 CA COPYRIGHT 1999 ACS  
AN 124:124693 CA  
TI Ion beam assisted deposition of ZrO<sub>2</sub> thin films  
AU Neubeck, K.; Nitsche, R.; Hahn, H.; Alberts, L.; Wolf, G. K.; Friz, M.  
CS Materials Science Dep., Technical Univ. Darmstadt, Darmstadt, Germany  
SO Nucl. Instrum. Methods Phys. Res., Sect. B (1995), 106(1-4), 110-15  
CODEN: NIMBEU; ISSN: 0168-583X  
DT Journal  
LA English  
CC 57-2 (Ceramics)  
AB Microstructure and properties of thin films can be modified by ion beam irradn. during growth. The stoichiometry, d., crystallinity, and texture of ZrO<sub>2</sub> films deposited under ion beam impact on glassy carbon and silicon single crystals were investigated. Argon ion beams with an energy of 10 keV and a c.d. of 40 .mu.A/cm<sup>2</sup> were used during electron beam evapn. of ZrO<sub>2</sub> pellets with a rate of 0.25 nm/s. The angle between substrate normal and ion beam was set at 0.degree., 15.degree.  
and 55.degree.. Stoichiometry of the films was analyzed by RBS. Film d. was calcd. from combined RBS anal. and thickness measurements by profilometer and spectrophotometer. Phase content, crystallinity, and texture were investigated by X-ray diffraction (XRD), four pole measurements and high resoln. transmission electron microscopy (HRTEM). Influence of the angle of incidence of ions on texture will be discussed.  
ST zirconia coating property ion beam deposition  
IT Vapor deposition processes

of (electron beam evapn.; stoichiometry, d., crystallinity, and texture  
ZrO<sub>2</sub> films deposited under argon ion beam impact during electron beam  
evapn. on glassy carbon and silicon single crystals)

IT Ions in solids  
(implanted, argon; stoichiometry, d.,  
crystallinity, and texture of ZrO<sub>2</sub> films deposited under argon  
ion beam impact during electron beam evapn. on glassy carbon  
and silicon single crystals)

IT 1314-23-4, Zirconium oxide (ZrO<sub>2</sub>), processes  
RL: PEP (Physical, engineering or chemical process); PRP (Properties);  
PROC (Process)  
(coatings; stoichiometry, d., crystallinity, and texture of ZrO<sub>2</sub> films  
deposited under argon ion beam impact during electron beam evapn. on  
glassy carbon and silicon single crystals)

IT 7440-44-0, Carbon, uses  
RL: NUU (Nonbiological use, unclassified); USES (Uses)  
(glassy, substrates; stoichiometry, d., crystallinity, and texture of  
ZrO<sub>2</sub> films deposited under argon ion beam impact during electron beam  
evapn. on glassy carbon and silicon single crystals)

IT 7440-21-3, silicon, uses  
RL: NUU (Nonbiological use, unclassified); USES (Uses)  
(substrates; stoichiometry, d., crystallinity, and texture of ZrO<sub>2</sub>  
films deposited under argon ion beam impact during electron beam  
evapn.  
on glassy carbon and silicon single crystals)

L23 ANSWER 11 OF 31 CA COPYRIGHT 1999 ACS  
AN 119:192839 CA  
TI Optical investigation of implantation damage in gallium arsenide/aluminum  
gallium arsenide quantum wells  
AU Kieslich, A.; Straka, J.; Forchel, A.; Stoffel, N. G.  
CS Univ. Wuerzburg, Wuerzburg, D-8700, Germany  
SO Nucl. Instrum. Methods Phys. Res., Sect. B (1993), B80-81(Pt. 1), 616-19  
CODEN: NIMBEU; ISSN: 0168-583X  
DT Journal  
LA English  
CC 76-3 (Electric Phenomena)  
AB The authors used optical spectroscopy to study the depth range  
distribution of Ar+ implantation induced damage at  
ion energies between 15 and 170 keV. The photoluminescence  
efficiency of implanted GaAs/(Ga,Al)As quantum wells is detd. as  
a function of the ion energy and the angle of incidence. The  
evidence for damage by channeled ions is investigated by varying the  
incidence angle of the Ar ion beam through  
the major crystallog. axes of the sample. Implantations along  
the axial channels of the zinc-blende crystal lead to a dramatic decay of  
the photoluminescence intensity from quantum wells much deeper than in  
the case of random incidence. In particular, channeling simulations with a  
new mol. dynamics program reproduce the exptl. obstd. energy and angular  
dependence of the damage due to channeled ions.  
ST arsenide IIIA quantum well implantation damage; aluminum gallium  
arsenide well implantation damage; argon ion  
implantation IIIA arsenide well; luminescence IIIA arsenide well  
implantation damage  
IT Luminescence  
(of argon-ion-implanted gallium  
arsenide/aluminum gallium arsenide quantum-well structures)  
IT Semiconductor devices  
(quantum-well, gallium arsenide/aluminum gallium arsenide,  
implantation  
damage in, optical study of)  
IT 14791-69-6, Argon(1+), properties  
RL: PRP (Properties)  
(damage in gallium arsenide/aluminum gallium arsenide quantum-well

structures implanted with, optical study of)  
IT 1303-00-0, Gallium arsenide, uses  
RL: USES (Uses)  
(implantation damage in quantum-well structures from aluminum gallium arsenide and, optical study of)  
IT 106070-09-1, Aluminum gallium arsenide (Al<sub>0.3</sub>Ga<sub>0.7</sub>As)  
RL: USES (Uses)  
(implantation damage in quantum-well structures from gallium arsenide and, optical study of)

L23 ANSWER 14 OF 31 CA COPYRIGHT 1999 ACS  
AN 118:91967 CA  
TI Investigation of random and channeling argon(1+) implantation-induced damage in aluminum (indium) gallium arsenide/gallium arsenide quantum wells  
AU Kieslich, Albrecht; Straka, Josef; Forchel, Alfred  
CS Univ. Wuerzburg, Wuerzburg, D-8700, Germany  
SO Jpn. J. Appl. Phys., Part 1 (1992), 31(12B), 4428-32  
CODEN: JAPNDE; ISSN: 0021-4922  
DT Journal  
LA English  
CC 76-3 (Electric Phenomena)  
AB Ar<sup>+</sup> ion implantation at energies up to 170 keV in GaAs/GaAlAs and InGaAs/GaAs quantum wells is used to study the profile of the implantation induced damage as a function of the implantation parameters like the ion energy, the ion dose and the angle of incidence. The photoluminescence (PL) emission intensity of single quantum wells (SQW) at different positions in the layer structure is used as a local probe for the study of the damage. The influence of ion channeling on the damage is studied by varying the angle of incidence of the ion beam systematically through the major crystallog. axes of the sample. The authors observe even for random implantation a wide extension of the defect profiles, which can be described by a characteristic decay length due to a long ranging exponential tail of the damage profile. Compared to the results of random incidence ion implantation along the (100), (110), (111), and (211) axis leads to effective extensions of the damage up to a factor of .apprx.4 due to ion channeling.  
ST quantum well damage argon ion implantation;  
aluminum gallium arsenide quantum well; gallium arsenide quantum well  
IT Luminescence  
(of aluminum gallium arsenide-gallium arsenide quantum wells,  
argon ion implantation effect on)  
IT Semiconductor devices  
(quantum-well, aluminum gallium arsenide-gallium arsenide, damage in,  
induced by argon ion implantation)  
IT 14791-69-6, Argon ion(1+), miscellaneous  
RL: MSC (Miscellaneous)  
(damage induced by implantation of, in gallium arsenide-aluminum gallium arsenide quantum wells)  
IT 1303-00-0, Gallium arsenide, miscellaneous  
RL: MSC (Miscellaneous)  
(quantum well from, with aluminum gallium arsenide, damage in, induced by arsenic ion implantation)  
IT 37382-15-3, Aluminum gallium arsenide ((Al,Ga)As)  
RL: USES (Uses)  
(quantum well from, with gallium arsenide, damage in, induced by argon ion implantation)

L23 ANSWER 22 OF 31 CA COPYRIGHT 1999 ACS  
AN 101:158173 CA  
TI The applications of acoustic methods to study the properties of implanted layers  
AU Adliene, D.; Basin, V.; Daugela, J.; Joneliunas, S.; Pranevicius, L.

CS Kaunas Polytech. Inst., Kaunas, USSR  
SO Proc. Int. Ion Eng. Congr. (1983), Volume 3, 1849-54. Editor(s): Takagi,  
Toshinori. Published Int. Ion Eng. Congr., Kyoto, Japan.  
CODEN: 52KDA2

DT Conference  
LA English  
CC 65-6 (General Physical Chemistry)  
Section cross-reference(s): 75, 76

AB During **implantation** of 100-keV He<sup>+</sup> and Ar<sup>+</sup> ions in glass and Si, the velocity [V] (as obsd. by SEM) of the surface acoustic waves increased, which were used to study the **implantation**. The obsd. increases in V were interpreted in terms of changes in the surface shear modulus and d. caused by the ion **implantation**. For a LiNbO<sub>3</sub> crystal **implanted** with 100-keV H<sup>+</sup> ions along the (111) channel, the backscattering of channeling 500-keV protons was used to study the ion-beam-induced acoustic-emission intensity (I) as a function of the angle (.theta.) of disorientation between the ion beam and the (111) channel. The values of I and the no. of backscattered protons were min. for .theta. = 00.

ST surface acoustic wave ion **implantation**; helium ion  
**implantation** glass silicon; argon ion  
**implantation** glass silicon; silicon  
**implantation** argon helium ion; glass  
**implantation** argon helium ion; sound emission  
ion beam induced; channeling proton lithium niobate sound; backscattering proton lithium niobate sound

IT Glass, oxide  
Glass, oxide  
RL: PRP (Properties)  
    (**implantation** of argon and helium **ions**  
    in, surface-acoustic-wave velocity in study of)

IT Sound and Ultrasound, chemical and physical effects  
    (in ion **implantation** study in glass and **silicon**)

IT Sound and Ultrasound  
    /ion-beam-induced emission of, from lithium niobate, proton  
    backscattering in study of)

IT 7440-21-3, properties  
RL: PRP (Properties)  
    (**implantation** of argon and helium **ions**  
    in, surface-acoustic-wave velocity in study of)

IT 14234-48-1, properties 14791-69-6, properties  
RL: PRP (Properties)  
    (**implantation** of, in glass and **silicon**, surface-acoustic-wave  
    velocity in study of)

IT 12586-59-3, chemical and physical effects  
RL: PEP (Physical, engineering or chemical process); PROC (Process)  
    (in ion-beam-induced acoustic emission study)

IT 12031-63-9  
RL: PRP (Properties)  
    /ion-beam-induced acoustic emission from, proton backscattering in  
    study of)